Abstracts

Novel three-dimensional vertical interconnect technology for microwave and RF applications

K. Goverdhanam, R.N. Simons and L.P.B. Katehi. "Novel three-dimensional vertical interconnect technology for microwave and RF applications." 1999 MTT-S International Microwave Symposium Digest 99.2 (1999 Vol. II [MWSYM]): 641-644 vol.2.

In this paper, novel 3D interconnects suitable for applications in microwave and RF integrated circuit technology have been presented. The interconnect fabrication process and design details are presented. In addition, measured and numerically modeled results of the performance of the interconnects have been shown. The results indicate that the proposed technology has tremendous potential applications in integrated circuit technology.

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